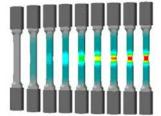
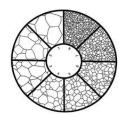
Engineering 4L - Section #55105





**Instructor:** Dr. John Heathcote **Lab Times, Location:** Tuesdays, 2:00-4:50pm, PHY-70

**Office:** Reedley College, FEM-1B (in Math Center, in FEM Building)

**Phone:** (559) 638-0300 ext. 3215

**e-mail:** john.heathcote@reedleycollege.edu

**Office Hours:** MW, 10:00-11:50AM, F, 11:00-11:50AM

If you cannot make regular office hours, feel free to make an appointment.

**Required Text:** None (However, the topics of this laboratory course will coincide with the topics

covered in ENGR 4 and in its textbook, Callister, William D. and Rethwisch, David G., Fundamentals of Materials Science and Engineering, An Integrated Approach, 5<sup>th</sup>

Edition, Wiley, 2015.

**Prerequisites:** CHEM 1A, PHYS 4A

Catalog Description: This is a laboratory course in which students investigate the structure, properties, and

performance of engineering materials, with topics including crystal structures, metallography, cold working and heat treatment, mechanical behavior, ductile and brittle failure, toughness, fatigue, corrosion, and properties of semiconductor devices.

**Grading:** 60% Laboratory Exercises and Reports

15% Lab Ouizzes

10% Presentation on a Topic in Materials Engineering

15% Final Exam

**Laboratory Exercises and Reports:** This is a laboratory course, so the major portion of the grade will be based upon the performance of labs and the reports that go along with these labs. Labs need to be performed on the week that they are scheduled. (Occasionally, a formal lab report will be assigned. This is to help prepare you for lab reports at the university level.)

**Lab Quizzes:** It is important for students to learn the lab techniques and the required calculations involved in the materials science topics. So, there will be many quizzes to test students' understanding of the material.

**Presentation on a Topic in Materials Engineering:** During the semester, you will research a topic in materials engineering and give a presentation to the class. Specific requirements for this presentation and your assigned presentation date will be announced during the semester.

**Final Exam**: During finals week, a comprehensive final exam will be given. This exam may cover both lab techniques and calculation problems.

**Grading Scale:** 90-100% A

80-89% B 70-79% C 60-69% D <60% F

Add Date:Friday, August 31Last day to add a courseDrop Date:Friday, October 12Last day to drop this course

Holidays: Monday, September 3 Labor Day Holiday

Monday, November 12 Veterans Day Holiday Thursday-Friday, November 22-23 Thanksgiving Holiday

Final Exam: Tuesday, December 11<sup>th</sup>, 2:00PM – 4:50PM

## **Accommodations for Students with Disabilities:**

If you have a verified need for an academic accommodation or materials in alternate media (i.e., Braille, large print, electronic text, etc.) per the Americans with Disabilities Act (ADA) or Section 504 of the Rehabilitation Act, please contact me as soon as possible.

**Course Outline:** (subject to change)

Lab Dates	Touries
Lab Dates	Topics
Tuesday, August 14th	Materials Classification and Properties
Tuesday, August 21st	Atomic Bonding
Tuesday, August 28 <sup>th</sup>	Metallic and Ceramic Unit Cells
Tuesday, September 4 <sup>th</sup>	Interstitials / Crystallography
Tuesday, September 11 <sup>th</sup>	Presentations / Lab Quiz #1
Tuesday, September 18 <sup>th</sup>	Tensile Testing – Elastic (Formal Report)
Tuesday, September 25 <sup>th</sup>	Tensile Testing
Tuesday, October 2 <sup>nd</sup>	Steel Heat Treatments
Tuesday, October 9th	Failure – Creep and Fatigue
Tuesday, October 16 <sup>th</sup>	Presentations / Lab Quiz #2
Tuesday, October 23 <sup>rd</sup>	Phase Diagrams
Tuesday, October 30 <sup>th</sup>	The Iron-Carbon System (Formal Report)
Tuesday, November 6 <sup>th</sup>	Electrical Resistivity
Tuesday, November 13 <sup>th</sup>	Semiconductor Devices
Tuesday, November 20th	Polymers
Tuesday, November 27 <sup>th</sup>	Presentations / Lab Quiz #3
Tuesday, December 4 <sup>th</sup>	Process Design
Tuesday, December 11 <sup>th</sup>	Final Exam

#### **COURSE OUTCOMES:**

Upon completion of this course, students will be able to:

- A. operate materials testing equipment and gather and analyze relevant data in order to measure material properties and/or evaluate processing treatments.
- B. write laboratory reports that communicate the collection, analysis, and interpretation of experimental data according to professional engineering standards.

#### **COURSE OBJECTIVES:**

In the process of completing this course, students will:

- A. model various crystal structures found in metals and nonmetals
- B. model crystal imperfections and analyze their effect on material properties
- C. measure stress-strain behavior for metals, polymers and ceramics
- D. investigate ductile and brittle fracture and identify the type of failure from fracture surfaces
- E. determine the relative toughness of various materials through impact testing
- F. evaluate fatigue behavior of metals
- G. analyze equilibrium phase diagrams and predict phases and microstructure present under certain conditions
- H. investigate the effect of various materials processing techniques (such as strain hardening, recrystallization, and precipitation hardening) on the structure and properties of metals
- I. assess the corrosion resistance of various materials under certain environmental conditions
- J. measure the behavior of semiconductor devices

#### LAB CONTENT:

- A. Materials Overview
  - 1. Classification of Materials
  - 2. Properties of Materials
  - 3. Materials Usage
- B. Crystal Structures
  - 1. Modeling
  - 2. Density and Packing Factor
  - 3. Crystal Imperfections

## C. Mechanical Behavior

- 1. Stress Strain Behavior
- 2. Elastic vs. Plastic Deformation
- 3. Ductile vs. Brittle Fracture
- 4. Hardness Testing
- 5. Toughness and Impact Testing
- 6. Fatigue loading and behavior

## D. Phase Diagrams

- 1. Interpreting phase diagrams
- 2. Experimental determination of phase diagrams
- 3. Prediction of phases and microstructures

# E. Metallography

- 1. Metallurgical Microscopy
- 2. Sample Preparation
- 3. Grain size measurements and characterization

## F. Cold Working and Heat Treatment

- 1. Effect of Cold Working on structure and properties
- 2. Effect of Heat Treatment on structure and properties
- 3. Evaluation of Materials Processing Treatments
  - i. Strain Hardening
  - ii. Recrystallization
  - iii. Precipitation Hardening
- G. Corrosion Resistance of various materials
- H. Electrical Properties of Materials
  - 1. Conductivity
  - 2. Properties of Semiconductor Devices